



BES2610WD

Brief Datasheet

Ultra-low Power Dual-mode Wi-Fi 6 and Bluetooth 5.4 Chip for Wireless Connectivity

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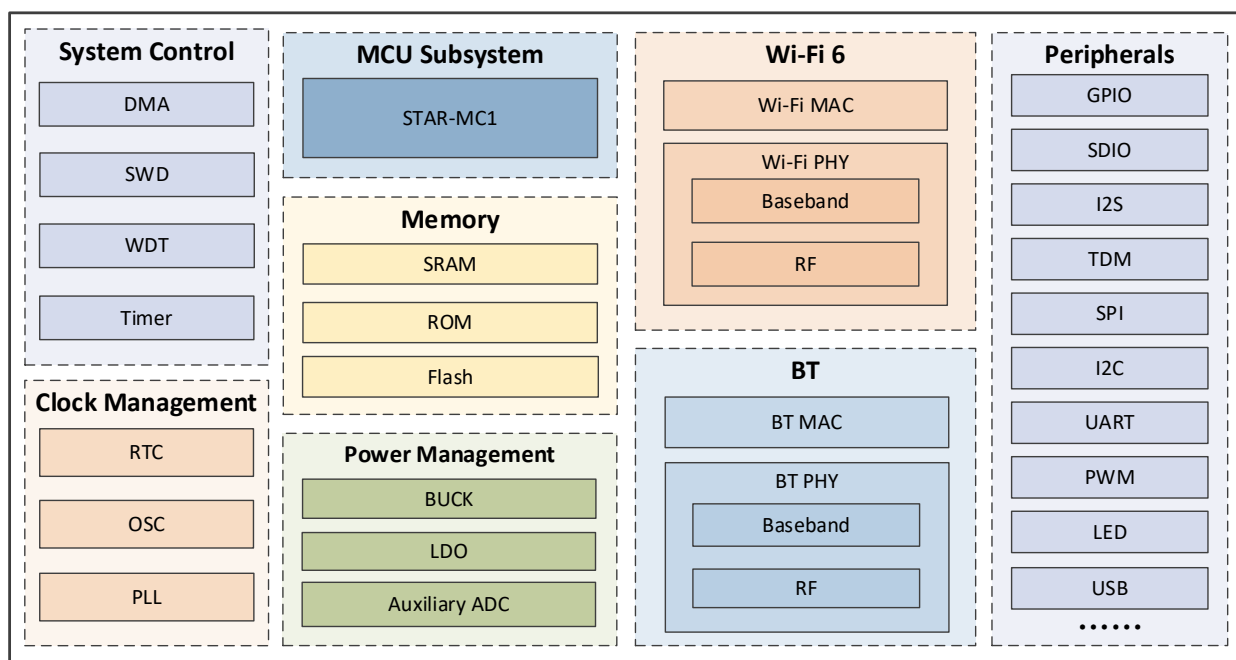
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1 General Description

The BES2610WD is an ultra-low power, highly integrated wireless connectivity chip designed for use in wearable applications. The platform incorporates a Wi-Fi 6 subsystem and a Bluetooth 6.1 subsystem, offering high-throughput wireless connectivity at high standards and cost-effective transmission over long distances. In addition, the platform incorporates a MCU subsystem comprising a STAR-MC1 processor, substantial SRAM, serial flash and a variety of interfaces.

The platform integrates an intelligent MAC design that includes a highly efficient offload engine and hardware data processing accelerators to completely offload Wi-Fi tasks from the host processor. The BES2610WD supports standards-based features for security, Quality of Service (QoS) and international regulations, delivering consistent reliable performance.



System Block Diagram

1.1 Applications

- Wireless connectivity for smart watches
- Other smart wearable devices

1.2 Features & Specifications*

Wi-Fi/Bluetooth Subsystem	Dual-band Wi-Fi IEEE 802.11a/b/g/n/ac/ax
	Dual-mode BT 6.1
CPU Subsystem	STAR-MC1
Memory and Storage	Shared 1.25 MB SRAM
	boot ROM
	Flash in package
Peripheral Interfaces	GPIO/SDIO/I2S/TDM/SPI/I2C/UART/PWM/LED/USB.....
Package	111-pin FCCSP

* The content in the table is subject to change without notice.